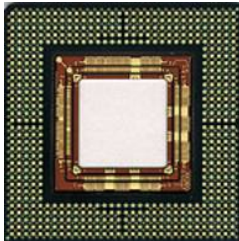
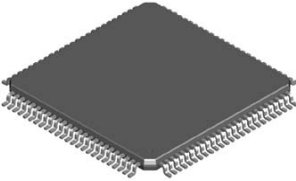
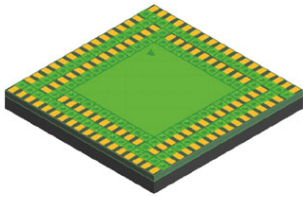
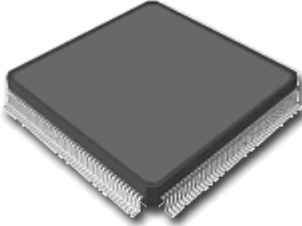
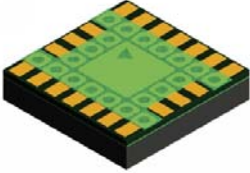

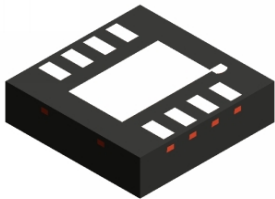
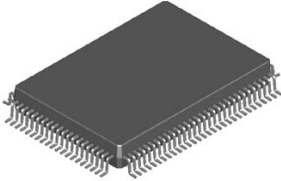
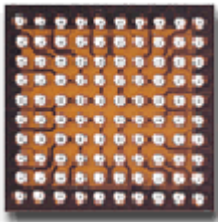
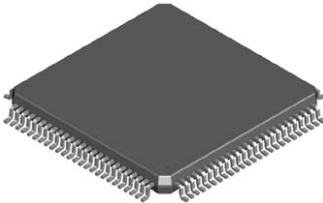
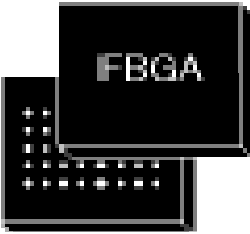
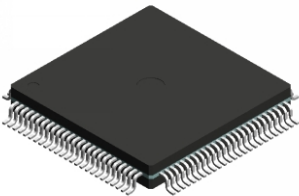
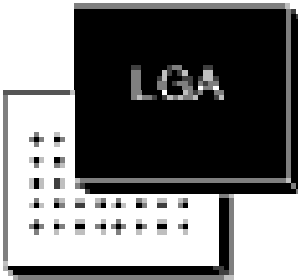





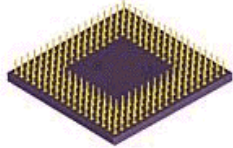

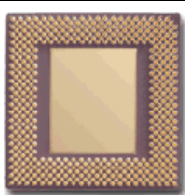
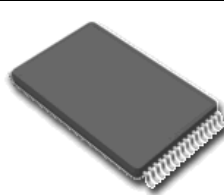
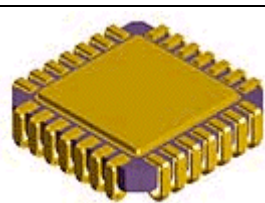


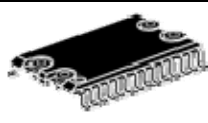

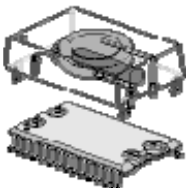
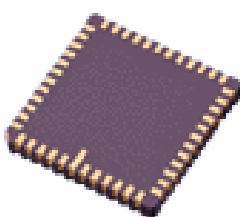
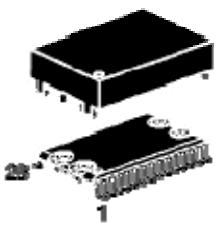


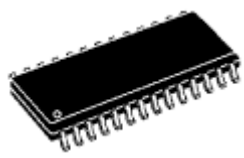
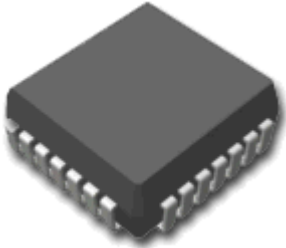
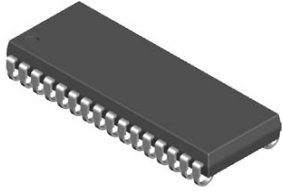
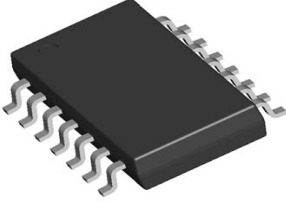
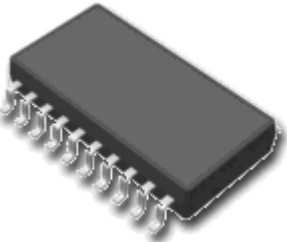
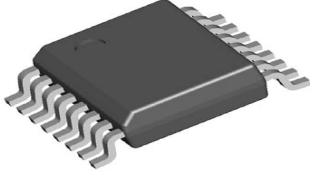
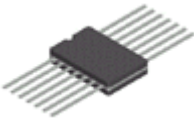
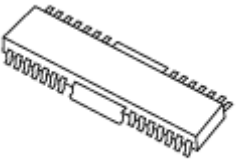
高密度封装 IC

序号	封装图	封装名称	序号	封装图	封装名称
1		BGA Ball Grid Array	16		TQFP 100L
2		LAMINATE CSP 112L Chip Scale Package	17		QFP Quad Flat Package
3		LAMINATE TCSP 20L Chip Scale Package	18		CERQUAD Ceramic Quad Flat Pack
4		LLP 8La	19		PQFP 100L
5		uBGA Micro Ball Grid Array	20		LQFP 100L
6		FBGA	21		METAL QUAD 100L
7		LGA	22		LQFP

8		uBGA Micro Ball Grid Array	23		PQFP
9		SBGA/SOT523	24		QFP Quad Flat Package
10		CPGA Ceramic Pin Grid Array	25		SOT26/SOT363
11		PGA Plastic Pin Grid Array	26		TSOP Thin Small Outline Package
12		CLCC	27		TSSOP or TSOP II Thin Shrink
13		JLCC	28		SOH
14		LDCC	29		SNAPTK/ SNAPZP
15			30		SNAPTK

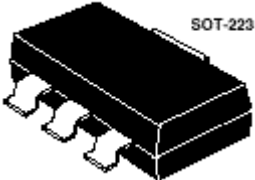
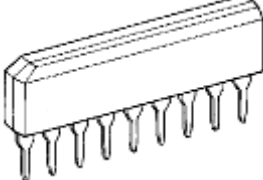

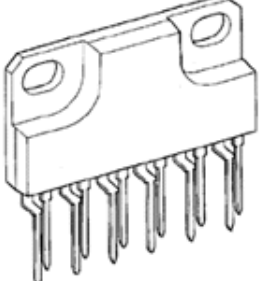







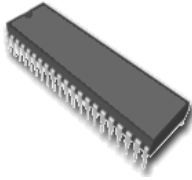

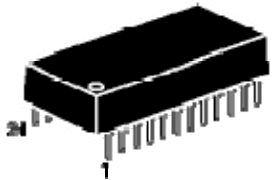

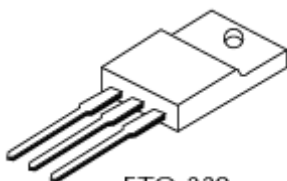
中密度封装 IC


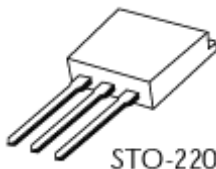
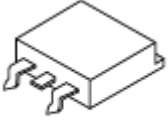
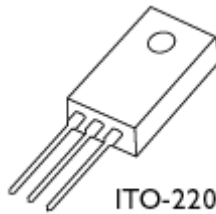

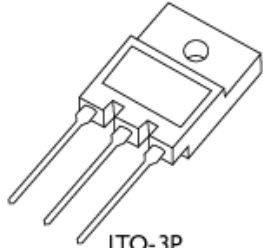

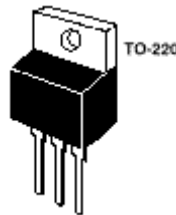



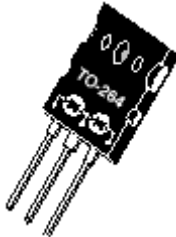


序号	封装图	封装名称	序号	封装图	封装名称
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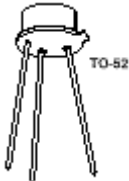




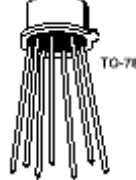

1		SO Small Outline Package	5		PLCC
2		SOJ 32L	6		SOP EIAJ TYPE II 14L
3		SSOP	7		SSOP 16L
4		Flat Pack	8	 HSOP-28	HSOP28

低密度封装及直插式 IC

序号	封装图	封装名称	序号	封装图	封装名称
1		SC-70 5L	22		PCDIP
2		SOT223	23		SDIP

3	 SOT-223	SOT223	24		SIP Single Inline Package
4	 SOT-23	SOT23	25		ZIP Zig-Zag Inline Package
5		SOT25/SOT353	26		PSDIP
6		SOT23/SOT323	27		PDIP
7		SOT343	28		FDIP
8		SOT89	29		SOT89
9		Gull Wing Leads	30		
10		TO252	31	 FTO-220	FTO220

11		TO263/T0268	32	 STO-220	SOT220
12	 STO-220	SOT220	33	 ITO-220	ITO220
13		Ceramic Case	34	 ITO-3P	ITO3p
14		C-Bend Lead	35	 TO-220	TO220
15	 TO-18	TO18	36	 TO-247	TO247
16		TO3	37	 TO-264	TO264
17		TO5	38	 TO-92	TO92

18	 <p>TO-52</p>	TO52	39	 <p>TO-39</p>	TO93
19		TO8	40	 <p>TO-99</p>	TO99
20	 <p>TO-71</p>	TO71	41	 <p>TO-78</p>	TO78
21	 <p>TO-72</p>	TO72	42		